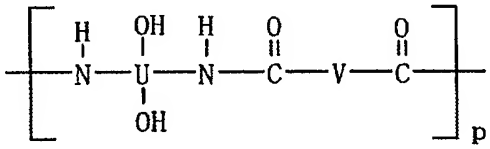
AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

1. (Currently amended) A photosensitive polymer composition comprising:

(a) a polyamide having a repeating unit represented by the following general formula (I):

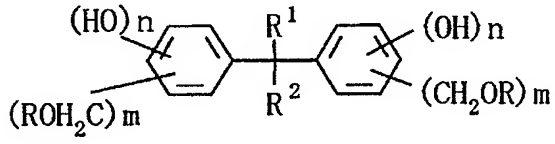


(I)

wherein U represents a tetravalent organic group, V represents a bivalent organic group and p is an integer representing a number of the repeating unit;

(b) a compound which generates an acid upon receiving light; and

(c) a compound represented by the following general formula (II):



(II)

wherein each of m and n ~~are each~~ represents independently an integer of 1 or 2, each of the Rs ~~are each~~ represents independently hydrogen, ~~alkyl group or acyl~~ a methyl group or an ethyl group, and each of R^1 and R^2 ~~each~~ independently represents a fluoroalkyl group having 1 to 3 carbon atoms.

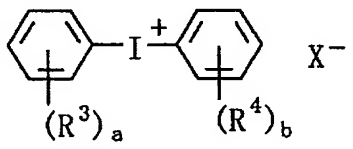
2. (Original) The photosensitive polymer composition according to claim 1, wherein the compound represented by the general formula (II) is 2,2-bis[3,5-bis(hydroxymethyl)-4-hydroxyphenyl]-1,1,1,3,3,3-hexafluoropropane.

3. (Original) The photosensitive polymer composition according to claim 1, wherein the compound represented by the general formula (II) is 2,2-bis[3,5-bis(methoxymethyl)-4-hydroxyphenyl]-1,1,1,3,3,3-hexafluoropropane.

4. (Previously presented) The photosensitive polymer composition according to claim 1, wherein ratios of the component (b) and the component (c) are 5 to 100 parts by weight and 1 to 30 parts by weight, respectively based on 100 parts by weight of the component (a).

5. (Previously presented) The photosensitive polymer composition according to claim 1, further comprising (d) a compound which reduces a solubility of the component (a) with respect to an alkali aqueous solution.

6. (Currently amended) The photosensitive polymer composition according to claim 5, wherein the component (d) is a diaryliodonium salt represented by the following general formula (III):



(III)

wherein X^- represents a counteranion, each of R^3 and R^4 ~~each~~ independently represents an alkyl group or an alkenyl group, and each of a and b ~~are each~~ represents independently an integer of 0 to 5.

7. (Original) The photosensitive polymer composition according to claim 5, wherein ratios of the component (b), the component (c) and the component (d) are 5 to 100 parts by weight, 1 to 30 parts by weight and 0.01 to 15 parts by weight, respectively based on 100 parts by weight of the component (a).

8. (Previously presented) A method of producing a pattern comprising the steps of:

applying the photosensitive polymer composition according to claim 1 on a support substrate and drying the photosensitive polymer composition;

exposing light to a photosensitive resin layer obtained by drying the photosensitive polymer composition to make a predetermined pattern;

developing the photosensitive resin layer after the exposing light; and

heat treating the photosensitive resin layer after the developing.

9. (Original) The method of producing the pattern according to claim 8, wherein an exposure light source used in the step of exposing generates i-line.

10. (Original) An electronic part comprising:

an electronic device having a layer of the pattern obtained by the method according to claim 8,

wherein the layer of the pattern is provided as an interlayer insulating film and/or a surface protection layer in the electronic device.

11. (New) The photosensitive polymer composition according to claim 1, wherein each of the Rs is hydrogen.

12. (New) The photosensitive polymer composition according to claim 1, wherein amount of said compound represented by the general formula (II) included in the composition is 1 to 30 parts by weight based on 100 parts by weight of said polyamide.

13. (New) The photosensitive polymer composition according to claim 1, wherein amount of said compound represented by the general formula (II) included in the composition is 5 to 20 parts by weight based on 100 parts by weight of said polyamide.

14. (New) The method of producing the pattern according to claim 8, wherein said developing is performed by removing portions of the photosensitive resin layer exposed to the light with an alkali aqueous developing solution.

15. (New) The method of producing the pattern according to claim 8, wherein said heat treating is performed at a temperature in a range of 150° to 450°C.